

**Space Solar Power Concept Technology Maturation**  
**Technical Interchange Meeting**  
**Glenn Research Center, Cleveland OH**  
**September 10-12, 2002**

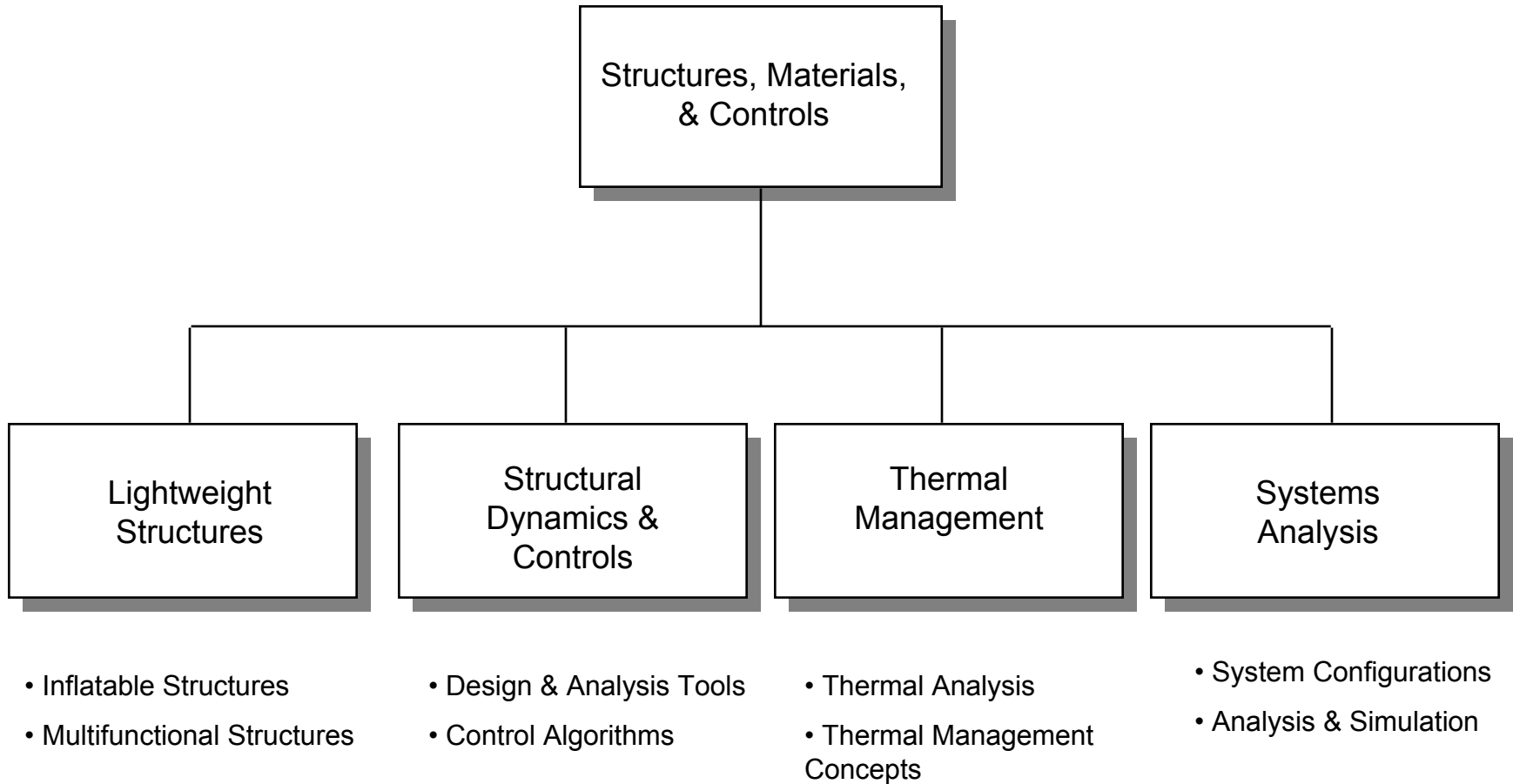
Output from Working Group Session: Structures, Materials, Assembly and, Thermal

Table 1

List of Revolutionary Technologies:

- 1)
- 2)
- 3)

# Work Breakdown Structure



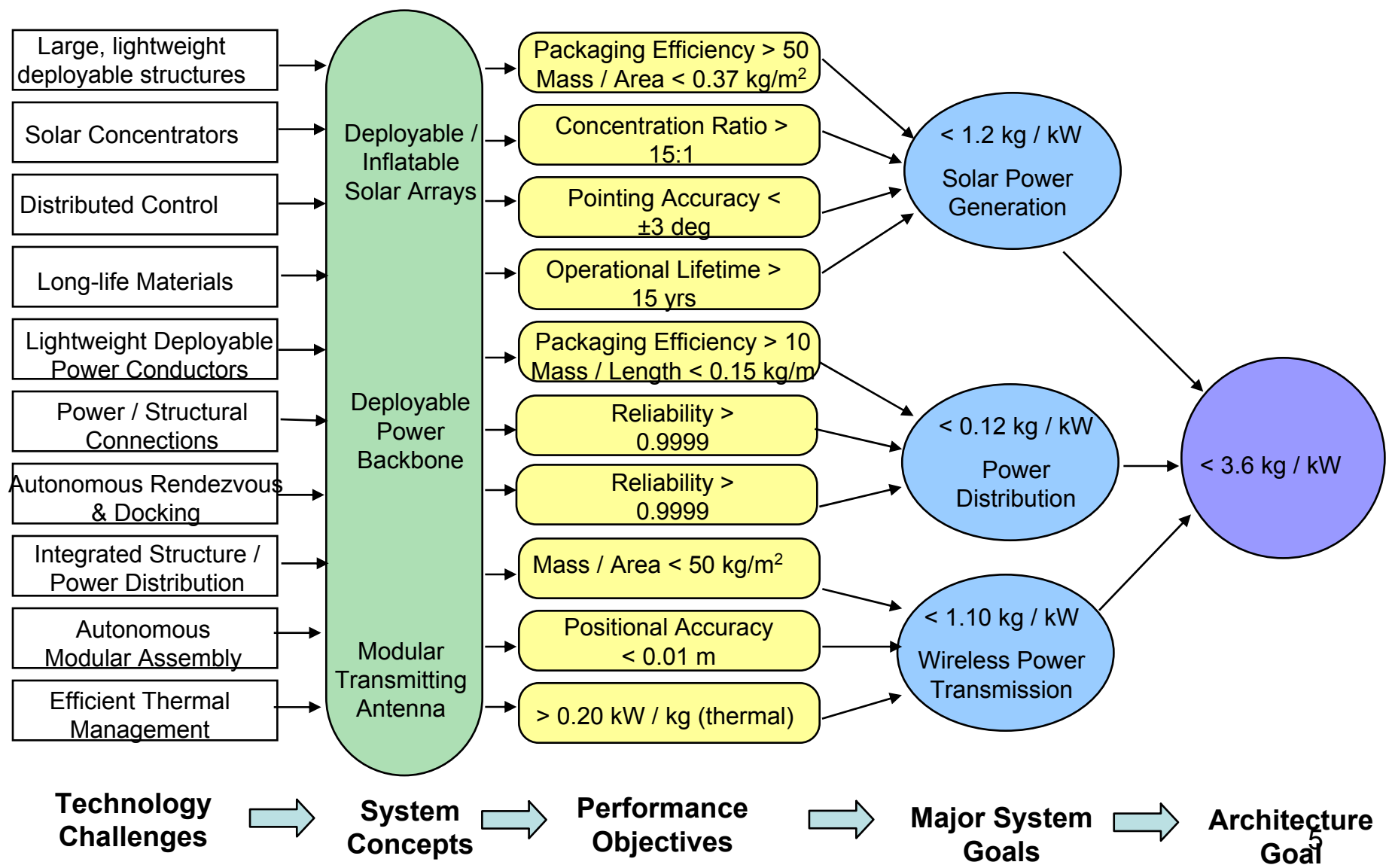
## Output from Working Group Session: Structures, Materials, Assembly and, Thermal

Table 2

Detailed description and assessment of technologies from Table 1. List the impact to the SSP goals and the other related technologies:

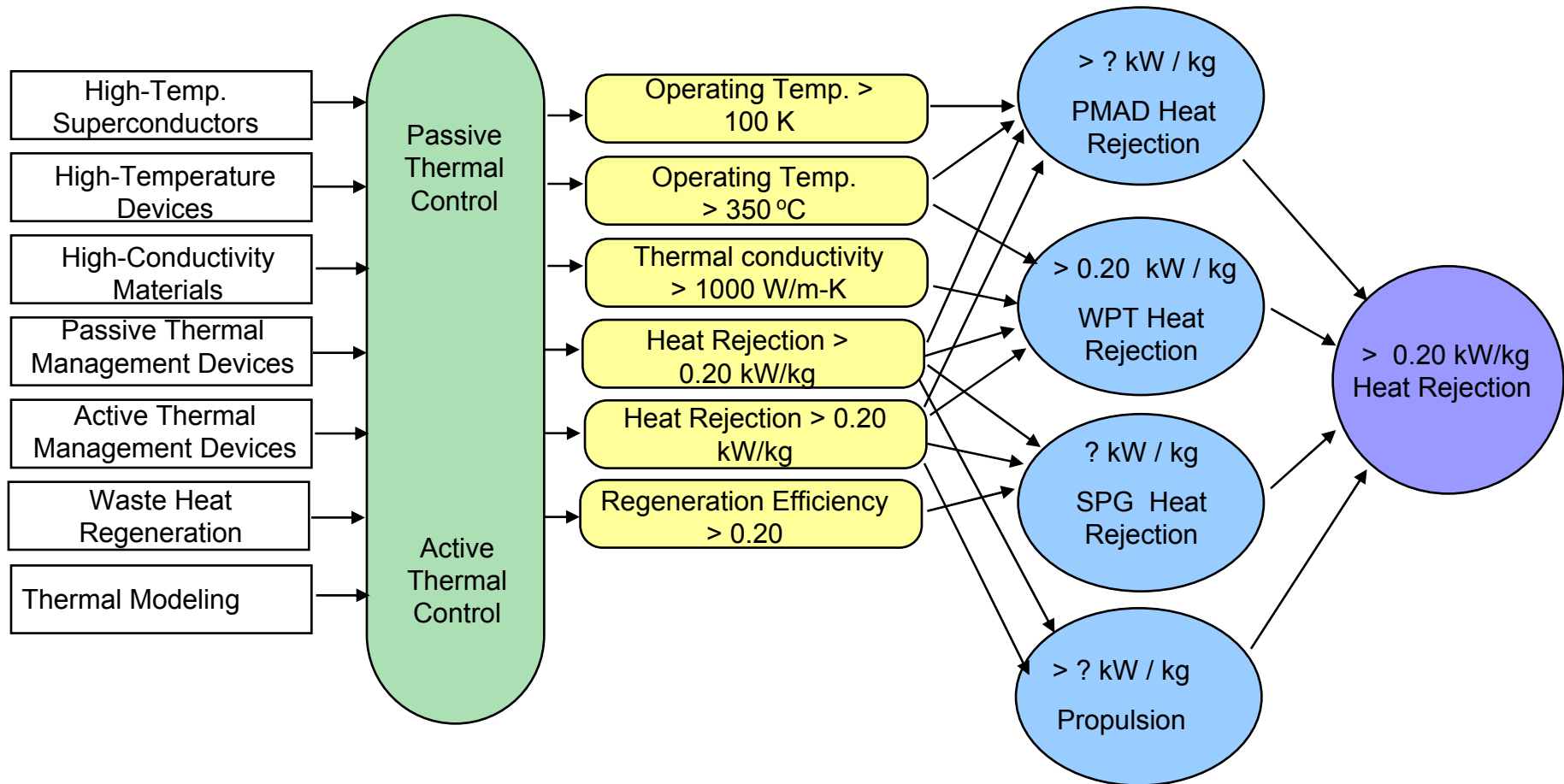
- 1)
- 2)
- 3)

STRUCTURES, MATERIALS, & CONTROLS  
Strategic Technology Approach



# THERMAL MANAGEMENT

## Strategic Technology Approach



**Technology  
Challenges**



**System  
Concepts**



**Performance  
Objectives**



**Major System  
Goals**



**Architecture  
Goal**

Output from Working Group Session: Structures, Materials, Assembly and, Thermal  
Table 3

*Consensus on the future direction of research and development to solve the challenges of SSP:*

**Near Term:**

- Need to baseline a laser based WPT and develop system level model for flow down of requirements to structures, thermal, and controls.
- Evaluate Multifunction arrays (PV, Diodes, MEMS, Thermal, Fiber Optic, Furlable, Packaging,...)
- Perform structural and thermal analysis of baseline for technology benefits assessment.
- Develop packaging schemes for single launch vehicle.

**Far Term:**

- Evaluate feasibility of solar pumped laser designs.
- Assess modular (scaled) systems (e.g. hybrid laser/microwave WPT)

## Summary

- The Structures and Thermal working group needs direction/help from SIWG and others in selecting a configuration for focused effort.
- During this Structures and Thermal working group, the main objective of the team was to evaluate new laser based WPT concepts and discuss thermal requirements.
- Opportunity exists for real advances in integrated design of multifunction arrays (PV, Diodes, MEMS, Thermal, Fiber Optic, Furlable, Packaging, Deployment, ...)